

Cond A1

96. An apparatus according to claim 92 further comprising a pump controller adapted to control a rate of evacuation of the gas in the chamber by changing a speed of the pump.

97. An apparatus for processing a substrate, the apparatus comprising:

- Sub B62
- (a) a chamber for holding the substrate; and
 - (b) a pump having an inlet connected to the chamber via a foreline for evacuating gas in the chamber, the foreline having an internal surface area of less than about 0.4 m^2 , and the pump having an outlet that exhausts the evacuated gas to atmospheric pressure.

98. An apparatus according to claim 97 wherein the foreline comprises a length of less than about 2 m.

99. An apparatus according to claim 97 wherein the foreline comprises a diameter of less than about 80 mm.

REMARKS

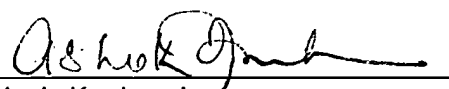
Newly added claims 65 to 99 are supported by the Specification at page 16, line 1, to page 19, line 5; and newly added claims 93 to 99 are supported by the Specification at page 14, lines 1 to 30, and by Figure 7. No new matter is added. Therefore, entry of the added claims is respectfully requested.

Should the Examiner have any questions regarding this Preliminary Amendment, the Examiner is requested to telephone Applicant's representative at the number listed below.

Respectfully submitted,

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